Material Declaration Report

Package Type:	**QFNWB3.5*3.5-14L(P0.50T0.85)**
Pericom Package Code:	**NA**
RoHS Compliance:	**Yes**
Applicable Exemption:	**N/A**

Component Weight (mg):	**37.330**
Termination Plating:	**Matte Tin**
JESD 97 Pb-free Category:	**e3**
Plating Thickness (um):	**10~20**
Tin Whisker Mitigation:	**Anneal, 150C/1hr**

MSL Rating:	**1**
Peak Body Temp (C):	**260**
Max Time (sec):	**30**
Reflow Cycles:	**3**
Rev Date:	**Nov 20,2012**

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	16.810	J	Silica	60676-86-0	84.50	14.20445
			Epoxy Resin	Trade Secret	5.50	0.92455
			Phenolic Resin	Trade Secret	3.50	0.58835
			Carbon Black	1333-86-4	0.20	0.03362
			Magn	Trade Secret	6.30	1.05903
LEAD FRAME	19.130		Cu	7440-50-8	97.37	18.62688
			Fe	7439-89-6	2.40	0.45912
			P	7723-14-0	0.10	0.01913
			Zn	7440-66-6	0.10	0.01913
			Pb	7439-92-1	0.03	0.00574
TERMINATION PLATING	0.510		Tin	7440-31-5	99.90	0.50949
			Impurity	Proprietary	0.10	0.00051
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.290		Silver	7440-22-4	78.00	0.22620
			Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	3.00	0.00870
			Epoxy resin,epichlorohydrin-dimer fatty acid	68475-94-5	3.00	0.00870
			Butyrolactone,gamma-	96-48-0	3.00	0.00870
			Poly(oxypropylene)diamine	9046-10-0	3.00	0.00870
			2,6-Diglycidyl phenyl allyl ether oligomer	NOT ASSIGNED	3.00	0.00870
			Organosilane(Trade Secret-10001)	TS ref# 10001	3.00	0.00870
			Copper(II) oxide	1317-38-0	3.00	0.00870
			Epoxy resin modifier(Trade Secret-10038)	TS ref# 10038	1.00	0.00290
GOLD WIRE	0.240		Au	7440-57-5	99.99	0.23998
			Other materials	Proprietary	0.01	0.00002

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.